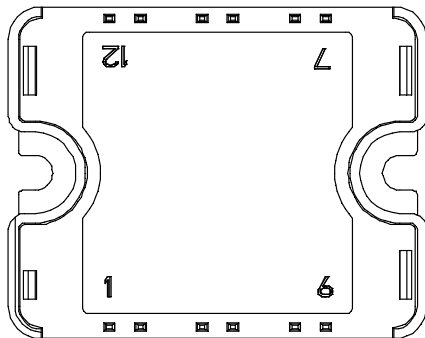
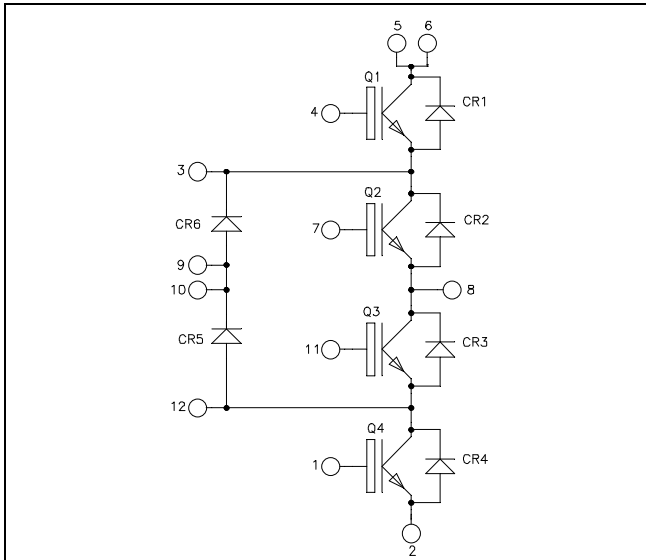


**Three level inverter  
Trench + Field Stop IGBT3  
Power Module**

**$V_{CES} = 600V$   
 $I_C = 50A @ T_c = 80^\circ C$**



All multiple inputs and outputs must be shorted together  
5/6 ; 9/10

**Application**

- Solar converter
- Uninterruptible Power Supplies

**Features**

- Trench + Field Stop IGBT3 Technology
  - Low voltage drop
  - Low tail current
  - Switching frequency up to 20 kHz
  - Soft recovery parallel diodes
  - Low diode VF
  - Low leakage current
  - RBSOA and SCSOA rated
- Very low stray inductance
- High level of integration

**Benefits**

- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive TC of VCEsat
- Low profile
- RoHS Compliant

**Q1 to Q4 Absolute maximum ratings**

| Symbol    | Parameter                             | Max ratings         | Unit        |
|-----------|---------------------------------------|---------------------|-------------|
| $V_{CES}$ | Collector - Emitter Breakdown Voltage | 600                 | V           |
| $I_C$     | Continuous Collector Current          | $T_C = 25^\circ C$  | 80          |
|           |                                       | $T_C = 80^\circ C$  | 50          |
| $I_{CM}$  | Pulsed Collector Current              | $T_C = 25^\circ C$  | 100         |
| $V_{GE}$  | Gate - Emitter Voltage                | $\pm 20$            | V           |
| $P_D$     | Maximum Power Dissipation             | $T_C = 25^\circ C$  | 176         |
| RBSOA     | Reverse Bias Safe Operating Area      | $T_J = 150^\circ C$ | 100A @ 550V |

**CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.  
See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

**Q1 to Q4 Electrical Characteristics**

| Symbol        | Characteristic                       | Test Conditions                             | Min | Typ                       | Max | Unit          |   |
|---------------|--------------------------------------|---|-----|---------------------------|-----|---------------|---|
| $I_{CES}$     | Zero Gate Voltage Collector Current  | $V_{GE} = 0\text{V}, V_{CE} = 600\text{V}$  |     |                           | 250 | $\mu\text{A}$ |   |
| $V_{CE(sat)}$ | Collector Emitter Saturation Voltage | $V_{GE} = 15\text{V}$<br>$I_C = 50\text{A}$ |     | $T_j = 25^\circ\text{C}$  | 1.5 | 1.9           | V |
|               |                                      |   |     | $T_j = 150^\circ\text{C}$ |     | 1.7           |   |
| $V_{GE(th)}$  | Gate Threshold Voltage               | $V_{GE} = V_{CE}, I_C = 600\mu\text{A}$     | 5.0 | 5.8                       | 6.5 | V             |   |
| $I_{GES}$     | Gate – Emitter Leakage Current       | $V_{GE} = 20\text{V}, V_{CE} = 0\text{V}$   |     |                           | 600 | nA            |   |

**Q1 to Q4 Dynamic Characteristics**

| Symbol       | Characteristic                      | Test Conditions  | Min                       | Typ  | Max  | Unit                      |
|--------------|-------------------------------------|--|---------------------------|------|------|---------------------------|
| $C_{ies}$    | Input Capacitance                   | $V_{GE} = 0\text{V}$<br>$V_{CE} = 25\text{V}$<br>$f = 1\text{MHz}$   |                           | 3150 |      | pF                        |
| $C_{oes}$    | Output Capacitance                  |  |                           | 200  |      |                           |
| $C_{res}$    | Reverse Transfer Capacitance        |  |                           | 95   |      |                           |
| $Q_G$        | Gate charge                         | $V_{GE} = \pm 15\text{V}, I_C = 50\text{A}$<br>$V_{CE} = 300\text{V}$  |                           | 0.5  |      | $\mu\text{C}$             |
| $T_{d(on)}$  | Turn-on Delay Time                  | Inductive Switching ( $25^\circ\text{C}$ )<br>$V_{GE} = \pm 15\text{V}$<br>$V_{Bus} = 300\text{V}$<br>$I_C = 50\text{A}$<br>$R_G = 8.2\Omega$  |                           | 110  |      | ns                        |
| $T_r$        | Rise Time                           |  |                           | 45   |      |                           |
| $T_{d(off)}$ | Turn-off Delay Time                 |  |                           | 200  |      |                           |
| $T_f$        | Fall Time                           |  |                           | 40   |      |                           |
| $T_{d(on)}$  | Turn-on Delay Time                  | Inductive Switching ( $150^\circ\text{C}$ )<br>$V_{GE} = \pm 15\text{V}$<br>$V_{Bus} = 300\text{V}$<br>$I_C = 50\text{A}$<br>$R_G = 8.2\Omega$ |                           | 120  |      | ns                        |
| $T_r$        | Rise Time                           |  |                           | 50   |      |                           |
| $T_{d(off)}$ | Turn-off Delay Time                 |  |                           | 250  |      |                           |
| $T_f$        | Fall Time                           |  |                           | 60   |      |                           |
| $E_{on}$     | Turn-on Switching Energy            | $V_{GE} = \pm 15\text{V}$<br>$V_{Bus} = 300\text{V}$<br>$I_C = 50\text{A}$<br>$R_G = 8.2\Omega$  | $T_j = 25^\circ\text{C}$  | 0.3  |      | mJ                        |
|              |                                     |  | $T_j = 150^\circ\text{C}$ | 0.43 |      |                           |
| $E_{off}$    | Turn-off Switching Energy           | $I_C = 50\text{A}$<br>$R_G = 8.2\Omega$  | $T_j = 25^\circ\text{C}$  | 1.35 |      | mJ                        |
|              |                                     |  | $T_j = 150^\circ\text{C}$ | 1.75 |      |                           |
| $I_{sc}$     | Short Circuit data                  | $V_{GE} \leq 15\text{V}; V_{Bus} = 360\text{V}$<br>$t_p \leq 6\mu\text{s}; T_j = 150^\circ\text{C}$  |                           | 250  |      | A                         |
| $R_{thJC}$   | Junction to Case Thermal Resistance |  |                           |      | 0.85 | $^\circ\text{C}/\text{W}$ |

**CR1 to CR4 diode ratings and characteristics**

| <i>Symbol</i>     | <i>Characteristic</i>                   | <i>Test Conditions</i>  |                        | <i>Min</i> | <i>Typ</i> | <i>Max</i> | <i>Unit</i> |
|-------------------|---|---|------------------------|------------|------------|------------|-------------|
| V <sub>RRM</sub>  | Maximum Peak Repetitive Reverse Voltage |   |                        | 600        |            |            | V           |
| I <sub>RM</sub>   | Maximum Reverse Leakage Current         | V <sub>R</sub> =600V  | T <sub>j</sub> = 25°C  |            |            | 150        | μA          |
|                   |   |   | T <sub>j</sub> = 150°C |            |            | 350        |             |
| I <sub>F</sub>    | DC Forward Current                      |   | T <sub>c</sub> = 80°C  |            | 30         |            | A           |
| V <sub>F</sub>    | Diode Forward Voltage                   | I <sub>F</sub> = 30A<br>V <sub>GE</sub> = 0V                      | T <sub>j</sub> = 25°C  |            | 1.6        | 2          | V           |
|                   |   |   | T <sub>j</sub> = 150°C |            | 1.5        |            |             |
| t <sub>rr</sub>   | Reverse Recovery Time                   | I <sub>F</sub> = 30A<br>V <sub>R</sub> = 300V<br>di/dt = 1800A/μs | T <sub>j</sub> = 25°C  |            | 100        |            | ns          |
|                   |   |   | T <sub>j</sub> = 150°C |            | 150        |            |             |
| Q <sub>rr</sub>   | Reverse Recovery Charge                 | I <sub>F</sub> = 30A<br>V <sub>R</sub> = 300V<br>di/dt = 1800A/μs | T <sub>j</sub> = 25°C  |            | 1.5        |            | μC          |
|                   |   |   | T <sub>j</sub> = 150°C |            | 3.1        |            |             |
| E <sub>rr</sub>   | Reverse Recovery Energy                 | I <sub>F</sub> = 30A<br>V <sub>R</sub> = 300V<br>di/dt = 1800A/μs | T <sub>j</sub> = 25°C  |            | 0.34       |            | mJ          |
|                   |   |   | T <sub>j</sub> = 150°C |            | 0.75       |            |             |
| R <sub>thJC</sub> | Junction to Case Thermal Resistance     |   |                        |            |            | 2.45       | °C/W        |

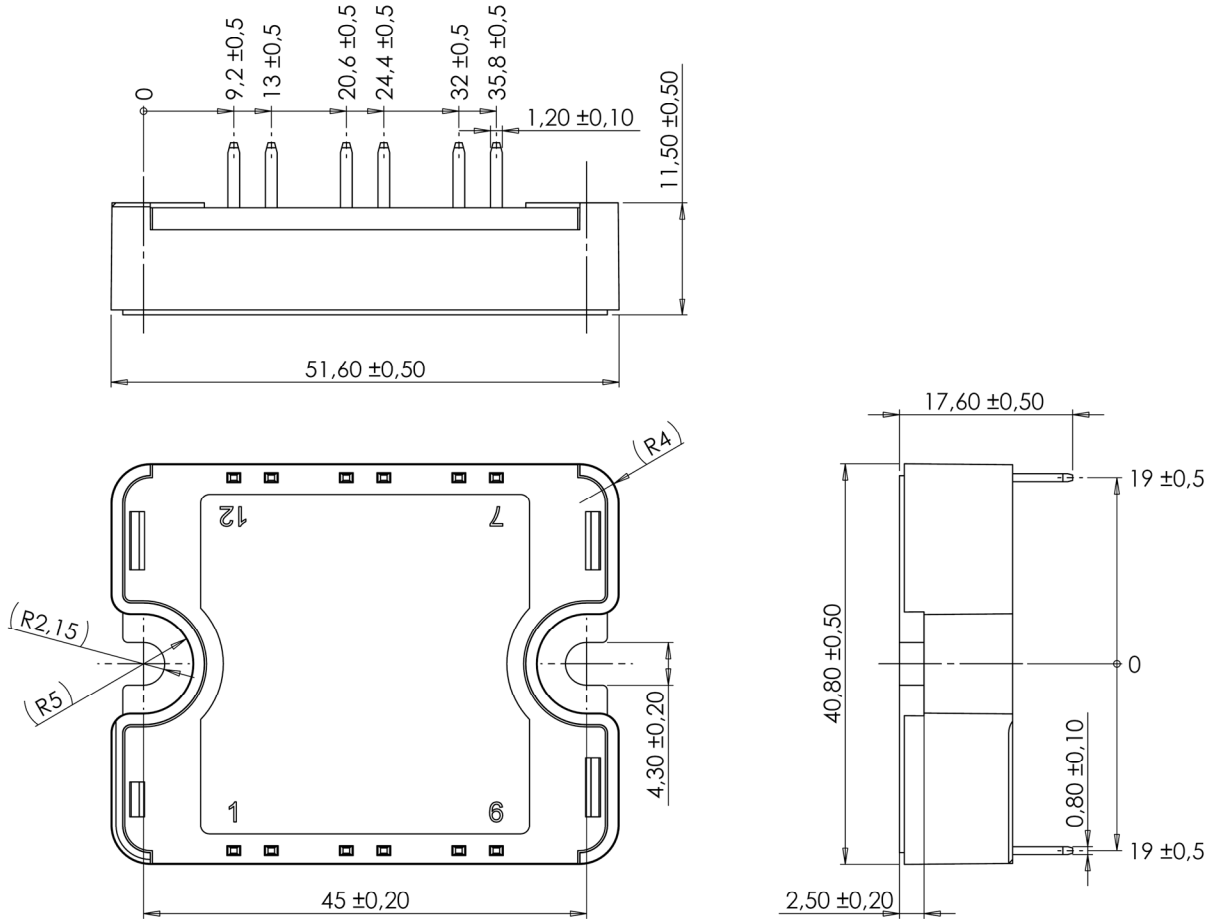
**CR5 & CR6 diode ratings and characteristics**

| <i>Symbol</i>     | <i>Characteristic</i>                   | <i>Test Conditions</i>  |                        | <i>Min</i> | <i>Typ</i> | <i>Max</i> | <i>Unit</i> |
|-------------------|---|---|------------------------|------------|------------|------------|-------------|
| V <sub>RRM</sub>  | Maximum Peak Repetitive Reverse Voltage |   |                        | 600        |            |            | V           |
| I <sub>RM</sub>   | Maximum Reverse Leakage Current         | V <sub>R</sub> =600V  | T <sub>j</sub> = 25°C  |            |            | 150        | μA          |
|                   |   |   | T <sub>j</sub> = 150°C |            |            | 350        |             |
| I <sub>F</sub>    | DC Forward current                      |   | T <sub>c</sub> = 80°C  |            | 50         |            | A           |
| V <sub>F</sub>    | Diode Forward Voltage                   | I <sub>F</sub> = 50A<br>V <sub>GE</sub> = 0V                      | T <sub>j</sub> = 25°C  |            | 1.6        | 2          | V           |
|                   |   |   | T <sub>j</sub> = 150°C |            | 1.5        |            |             |
| t <sub>rr</sub>   | Reverse Recovery Time                   | I <sub>F</sub> = 50A<br>V <sub>R</sub> = 300V<br>di/dt = 1800A/μs | T <sub>j</sub> = 25°C  |            | 100        |            | ns          |
|                   |   |   | T <sub>j</sub> = 150°C |            | 150        |            |             |
| Q <sub>rr</sub>   | Reverse Recovery Charge                 | I <sub>F</sub> = 50A<br>V <sub>R</sub> = 300V<br>di/dt = 1800A/μs | T <sub>j</sub> = 25°C  |            | 2.6        |            | μC          |
|                   |   |   | T <sub>j</sub> = 150°C |            | 5.4        |            |             |
| E <sub>rr</sub>   | Reverse Recovery Energy                 | I <sub>F</sub> = 50A<br>V <sub>R</sub> = 300V<br>di/dt = 1800A/μs | T <sub>j</sub> = 25°C  |            | 0.60       |            | mJ          |
|                   |   |   | T <sub>j</sub> = 150°C |            | 1.20       |            |             |
| R <sub>thJC</sub> | Junction to Case Thermal Resistance     |   |                        |            |            | 1.42       | °C/W        |

**Thermal and package characteristics**

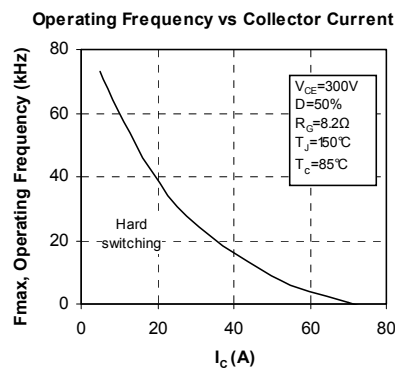
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|-------------------|--|-------------|----|------------|------------|------------|-------------|
| V <sub>ISOL</sub> | RMS Isolation Voltage, any terminal to case t = 1 min, 50/60Hz |             |    | 4000       |            |            | V           |
| T <sub>J</sub>    | Operating junction temperature range                           |             |    | -40        |            | 175        | °C          |
| T <sub>STG</sub>  | Storage Temperature Range                                      |             |    | -40        |            | 125        |             |
| T <sub>C</sub>    | Operating Case Temperature                                     |             |    | -40        |            | 100        |             |
| Torque            | Mounting torque  | To heatsink | M4 | 2          |            | 3          | N.m         |
| Wt                | Package Weight   |             |    |            |            | 80         | g           |

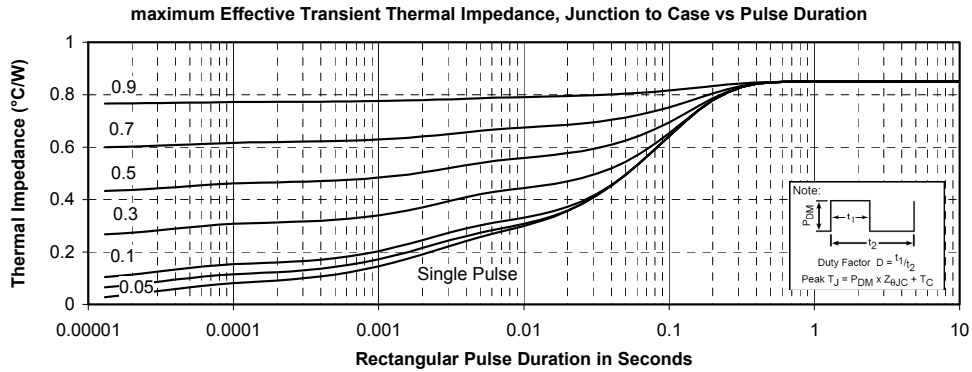
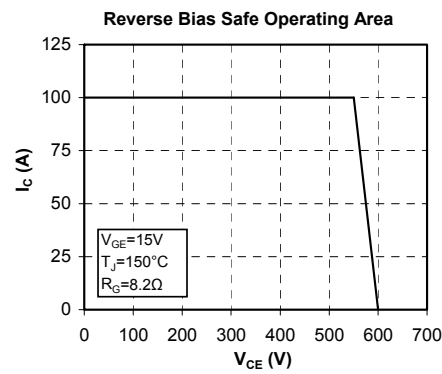
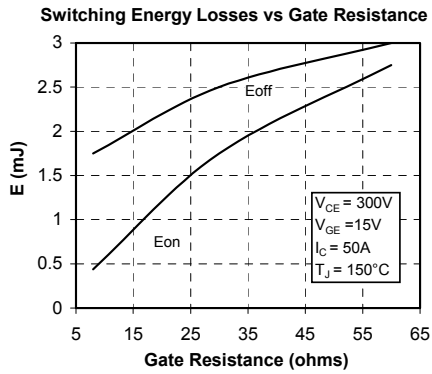
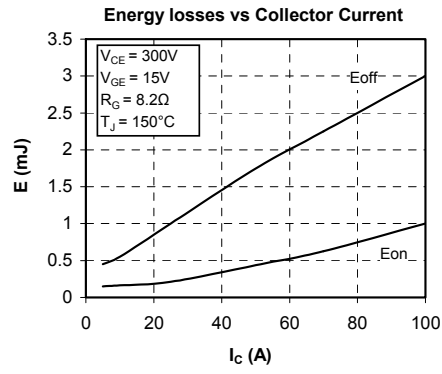
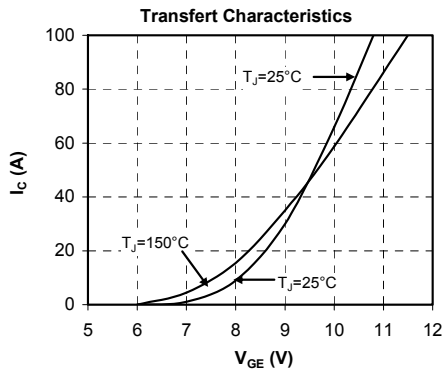
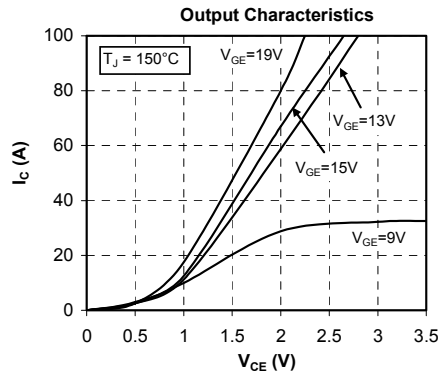
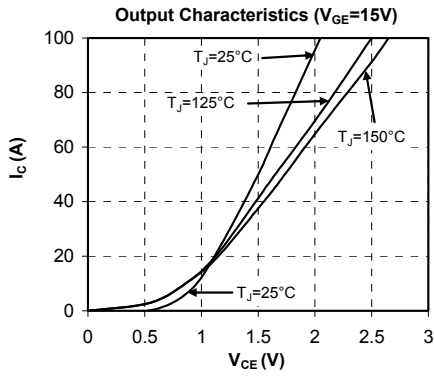
**SP1 Package outline** (dimensions in mm)

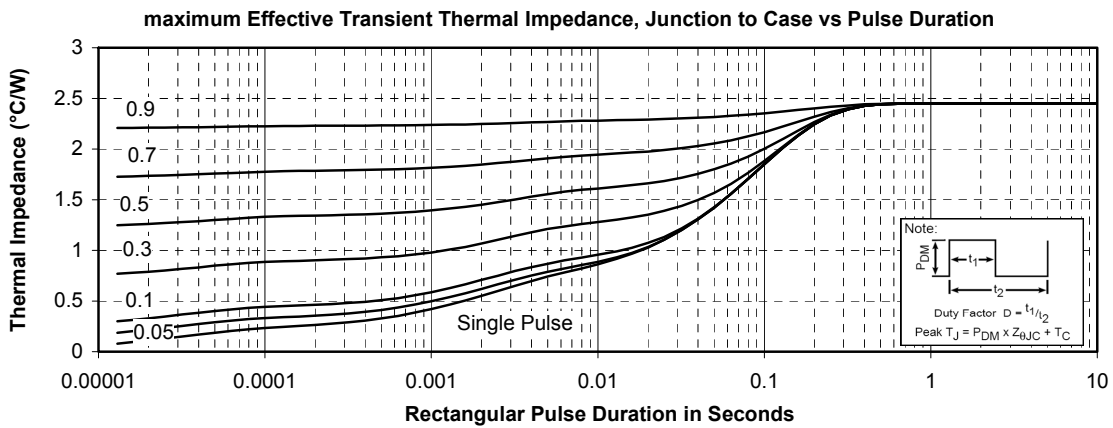
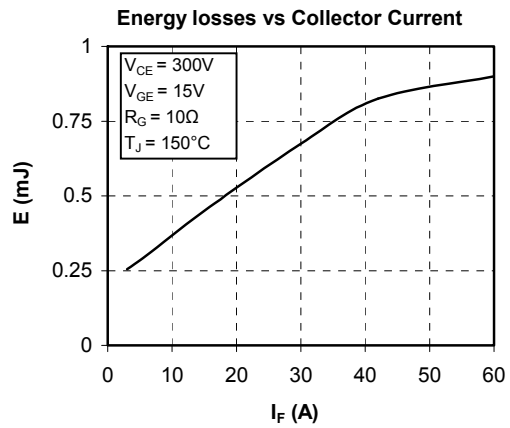
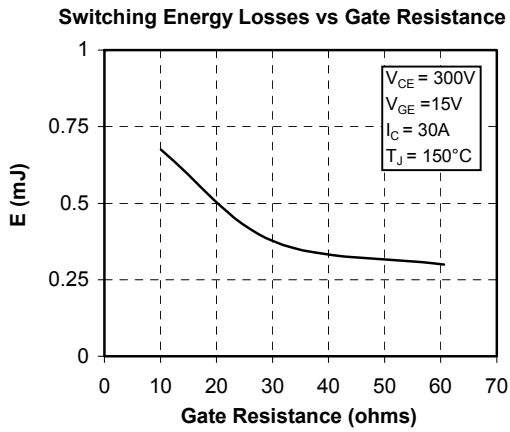
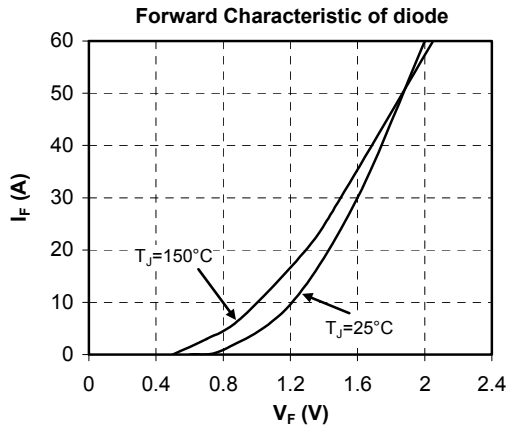


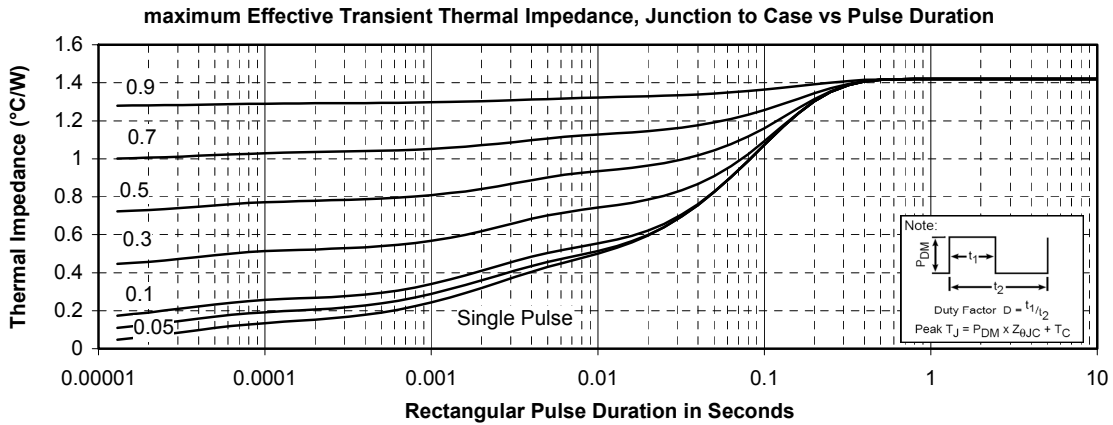
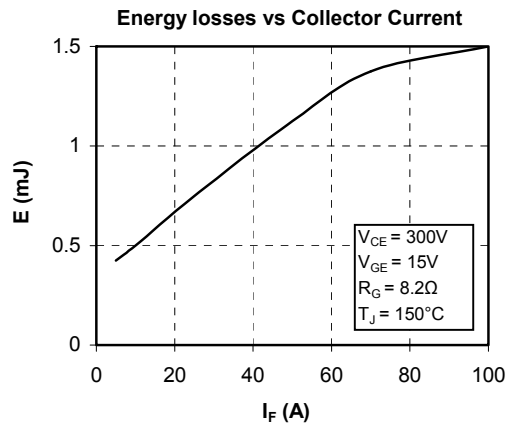
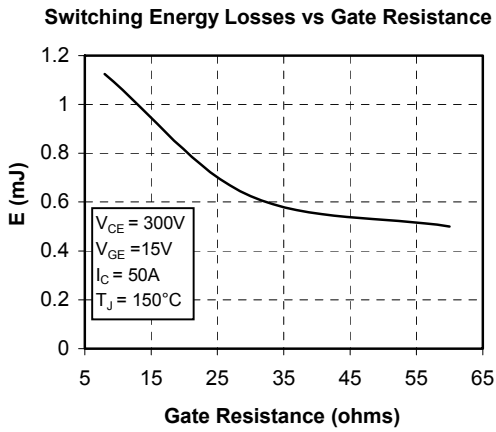
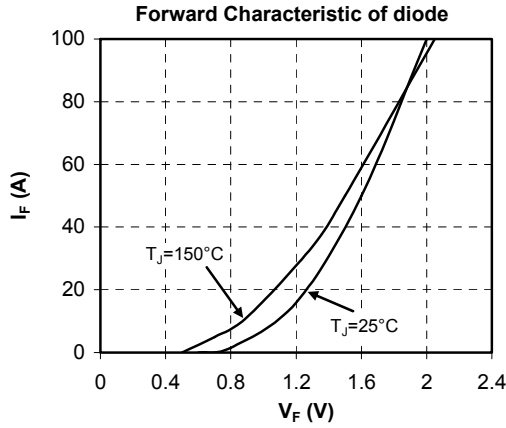
See application note 1904 - Mounting Instructions for SP1 Power Modules on [www.microsemi.com](http://www.microsemi.com)

**Q1 to Q4 Typical performance curve**





**CR1 to CR4 Typical performance curve**


**CR5 & CR6 Typical performance curve**


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